

S1A/B - S1M/B

1.0A SURFACE MOUNT GLASS PASSIVATED RECTIFIER

Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop and High Current Capability
- Surge Overload Rating to 30A Peak
- Ideally Suited for Automated Assembly

Mechanical Data

- Case: Molded Plastic
- Case Material UL Flammability Rating Classification 94V-0
- Moisture sensitivity: Level 1 per J-STD-020A
- Terminals: Solder Plated Terminal -Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band or Cathode Notch
- SMA Weight: 0.064 grams (approx.)
- SMB Weight: 0.093 grams (approx.)
- Marking: Type Number, See Page 2
- Ordering Information: See Page 2

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	SMA		SMB		
Dim	Min	Max	Min	Max	
Α	2.29	2.92	3.30	3.94	
В	4.00	4.60	4.06	4.57	
С	1.27	1.63	1.96	2.21	
D	0.15	0.31	0.15	0.31	
Е	4.80	5.59	5.00	5.59	
G	0.10	0.20	0.10	0.20	
Н	0.76	1.52	0.76	1.52	
J	2.01	2.62	2.00	2.62	
All Dimensions in mm					

A, B, D, G, J, K, M Suffix Designates SMA Package AB, BB, DB, GB, JB, KB, MB Suffix Designates SMB Package

Maximum Ratings and Electrical Characteristics T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic		Symbol	S1 A/AB	S1 B/BB	S1 D/DB	S1 G/GB	S1 J/JB	S1 K/KB	S1 M/MB	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V _{RRM} V _{RWM} V _R	50	100	200	400	600	800	1000	V
RMS Reverse Voltage		V _{R(RMS)}	35	70	140	280	420	560	700	V
Average Rectified Output Current	@ T _T = 100°C	lo	1.0					Α		
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed (JEDEC Method)	on rated load	I _{FSM}				30				А
Forward Voltage	@ I _F = 1.0A	V _{FM}	M 1.1			V				
	 Definition of the second secon	I _{RM}	5.0 100			μA				
Typical Total Capacitance (Note 1)		CT	10						pF	
Typical Thermal Resistance, Junction to Terminal (Note 2)		R _{0JT}	30						°C/W	
Operating and Storage Temperature Range		T _j , T _{STG}	-65 to +150					°C		

Notes: 1. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

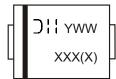
2. Thermal Resistance Junction to Terminal, unit mounted on PC board with 5.0 mm² (0.013 mm thick) copper pads as heat sink.

Ordering Information (Note 3)

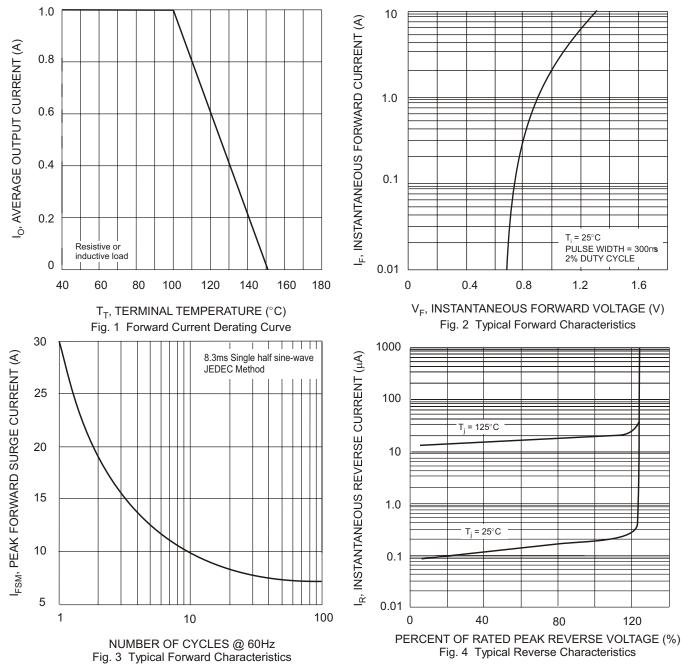
Device*	Packaging	Shipping
S1x-7	SMA	5000/Tape & Reel
S1xB-7	SMB	3000/Tape & Reel

Notes: 3. For Packaging Details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf. * x = Device type, e.g. S1A-7 (SMA package); S1AB-7 (SMB package).

Marking Information



XXX = Product type marking code, ex: S1A (SMA package) XXXX = Product type marking code, ex: S1AB (SMB package))! = Manufacturers' code marking YWW = Date code marking Y = Last digit of year ex: 2 for 2002 WW = Week code 01 to 52



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